



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

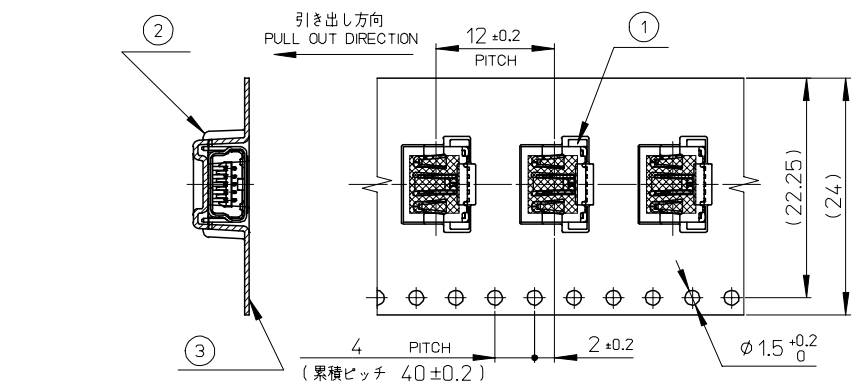
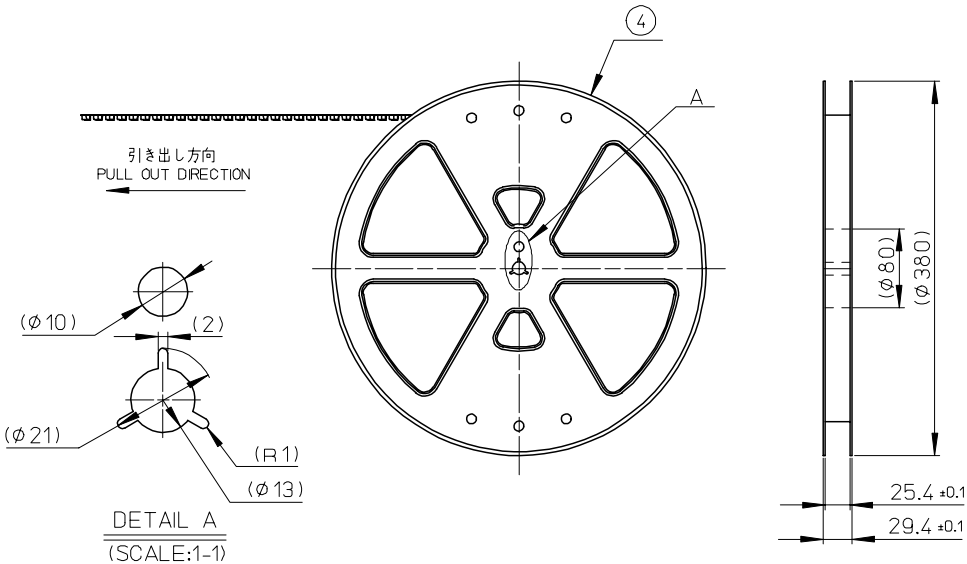
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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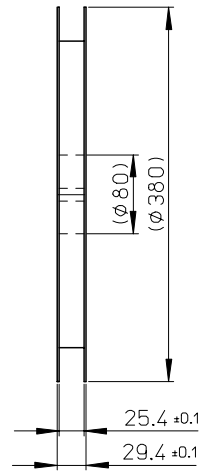
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



①	コネクタ CONNECTOR
②	エンボステープ EMBOSSSED TAPE
③	トップテープ TOP TAPE
④	リール REEL

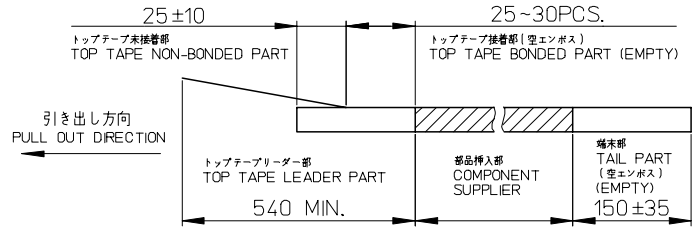


エンボステープ内の製品の向き  
DIRECTION OF PRODUCT  
IN EMBOSSSED TAPE  
(SCALE:2-1)

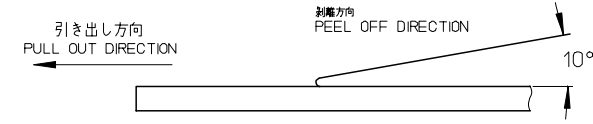


注記

- コネクタ詳細は SD-51387-006を参照下さい。  
REFER TO SD-51387-006
- 梱包数量: 1200個/リール  
NUMBER OF CONNECTOR : 1200 PCS/REEL
- リードテープ長さ  
LEAD TAPE LENGTH



- トップテープの剥離強度: 0.6 ±0.35N (60 ±35gf)  
<剥離速度: 300mm/min (参考)> (剥離方向は下図参照)  
PEEL-OFF FORCE OF TOP TAPE : 0.6 ±0.35N (60 ±35gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
<PEEL-OFF SPEED : 300mm/min (REF.)>



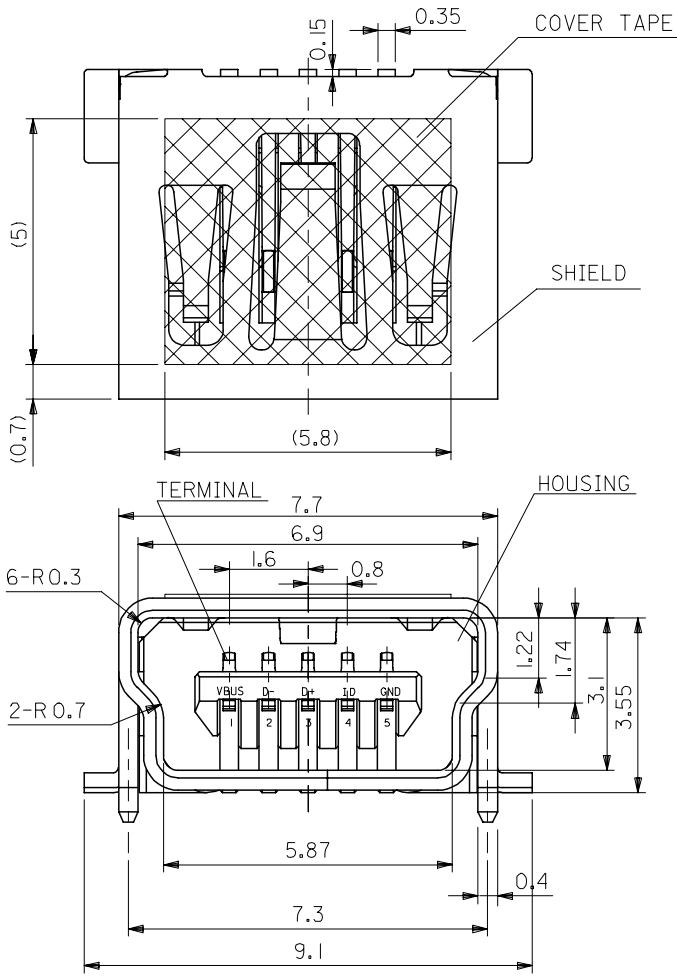
- 材料  
MATERIAL  
キャリアテープ: ポリプロピレン  
CARRIER TAPE : POLYPROPYLENE  
トップテープ : ポリエステル, ポリエチレン  
TOP TAPE : POLYESTER, POLYETHYLENE  
リール : ポリスチレン  
REEL : POLYSTYREN

51387-0530	51387-***0
製品番号 MATERIAL No.	MODEL No.

新編作成 EC NO: J2005-0570 DRAWN: MSHINYAMA 2004/08/30 CHKD: HTAKASE 2004/08/30 APPR: JMIYAZAW 2004/09/02 REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MSHINYAMA	DATE 04/07/18	TITLE EMBOSSSED TAPE PKG. FOR 51387-0539 -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/07/18	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY JMIYAZAWA	DATE 04/07/18	DOCUMENT NO. SD-51387-005	SHEET NO. 1 OF 1	
	ANGULAR	±3 °	MATERIAL NO. SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

F  
E  
D  
C  
B  
A



注記  
NOTES

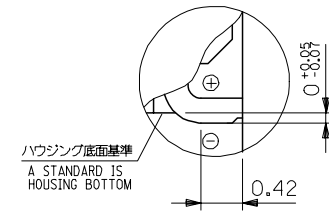
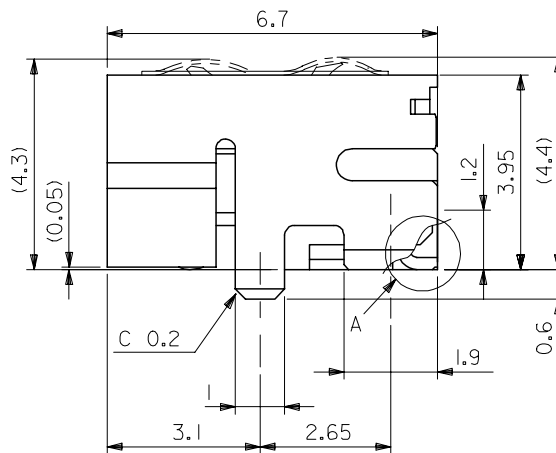
1. 材質

MATERIAL  
ハウジング:耐熱樹脂 ガラス充填, 黒色, UL94V-0  
HOUSING:HEAT RESISTANT PLASTIC,  
GLASS FILLED,BLACK,UL94V-0  
ターミナル:銅合金 (t=0.25)  
TERMINAL:COPPER ALLOY(t=0.25)  
シールド:銅合金 (t=0.4)  
SHIELD :COPPER ALLOY(t=0.4)  
カバー テープ:ポリイミド (t=0.08)  
COVER TAPE:POLYIMIDE (t=0.08)

2. メッキ仕様

PLATING  
ターミナル 接点部:金メッキ  
TERMINAL CONTACT AREA:GOLD  
半田付け部:錫メッキ  
SOLDER TAIL AREA:TIN  
下地部:ニッケルメッキ  
UNDER PLATING:NICKEL  
シールド:錫メッキ  
SHIELD :TIN  
下地部:ニッケル  
UNDER PLATING:NICKEL

3. 平坦度は0.1mm MAX.  
COPLANARITY 0.1mm MAX.



DETAIL A  
(SCALE 20:1)

5	51387-0539
極数 CKT.	製品番号 MATERIAL NO.

REVISED EC NO: J2007-2931 DRWN: AYOYAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY MSHINYAM	DATE 04/06/18	TITLE USB SERIES MINI-B REC. ASS'Y (REFLOW DIP TYPE) -LEAD FREE-			
	10 OVER 30 UNDER	±0.25	CHECKED BY HTAKASE	DATE 04/06/18				
	30 OVER	±0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

F

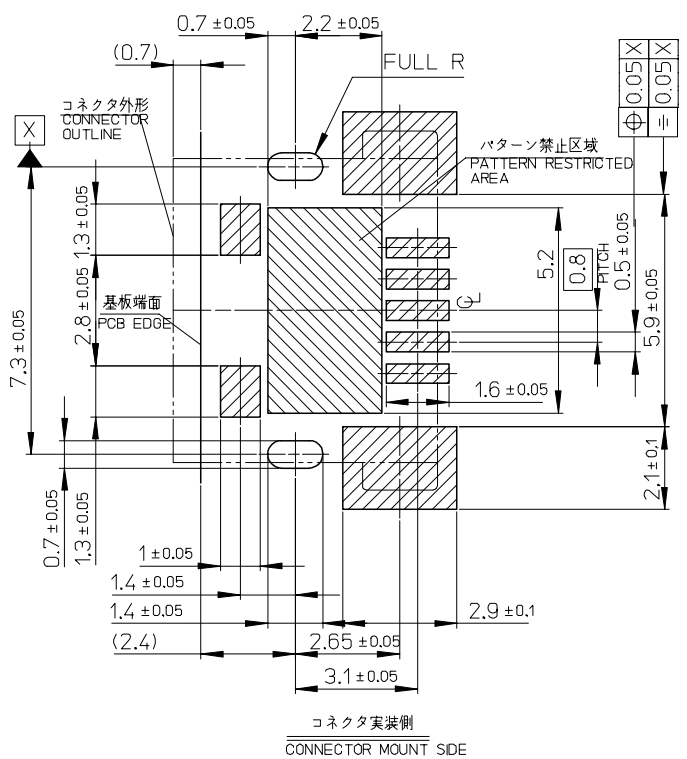
E

D

C

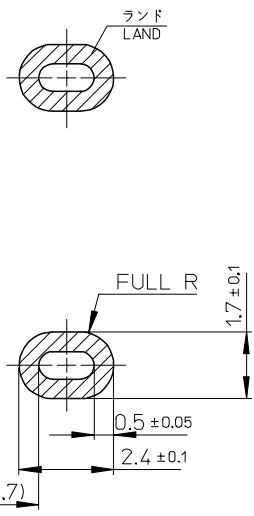
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A

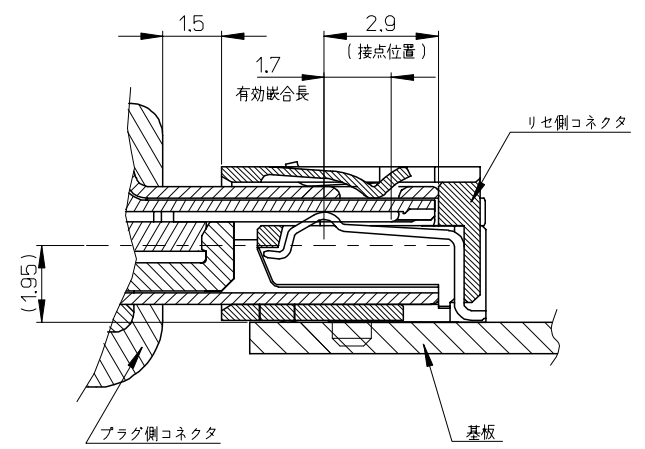


コネクタ実装側  
CONNECTOR MOUNT SIDE

推奨基板寸法 (SCALE 8:1)  
RECOMMENDED PCB PATTERN LAYOUT



逆側  
REVERSE SIDE



コネクタ嵌合図  
(SCALE 8:1)

REVISED EC NO: J2007-2931 DRWN: A0YAGI 2007/04/19 CHKD: YMAEDA 2007/04/23 APPR: NUKITA 2007/04/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
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	10 OVER 30 UNDER	± 0.25	CHECKED BY HTAKASE	DATE 04/06/18	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY JMIYAZAW	DATE 04/06/18	DOCUMENT NO. SD-51387-006	SHEET NO. 2 OF 2
	ANGULAR	± 3 °	MATERIAL NO. SEE SHEET 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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